



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AMENDMENT "A"

APPLICANTS: Sakan Iwashita et al. ATTY DOCKET NO: 09792909-5343  
SERIAL NO.: 10/080,313 GROUP ART UNIT: 2827  
DATE FILED: February 21, 2002 EXAMINER: Tuan T. Dinh  
INVENTION: "ELECTRONIC PARTS MOUNTING BOARD AND PRODUCTION METHOD THEREOF"

Hon. Assistant Commissioner for Patents  
Washington, DC 20231

S I R:

This Amendment "A" is filed in response to the Office Action of February 4, 2003. Please reconsider the application in view of the amendment and remarks presented below.

IN THE CLAIMS

Please cancel claims 1-6.

Please amend claim 7 as follows:

7. (Amended) A method of producing an electronics parts mounting board, comprising the steps of:

forming a circuit electrode board by forming a specific circuit electrode pattern on a surface of one side of a conductive base member to be plated and etched, by plating a specific conductive material thereon;

selectively forming a non-plated material on said circuit electrode board on which said circuit electrode pattern has been formed;

forming a projecting electrode for connection on said circuit electrode pattern by plating a specific conductive material on said circuit electrode pattern with said non-plated material used as a mask;

after removing said non-plated material, putting an insulating thermal bonding member between said circuit electrode board and a specific electrode circuit base member, pressing said projecting electrode of said circuit electrode board into said thermal bonding member so as to reach said electrode circuit base member, to bond said circuit electrode board to said electrode circuit base member; and

removing said entire conductive base member from a multilayer board obtained by bonding said circuit electrode board to said electrode circuit base member by etching.